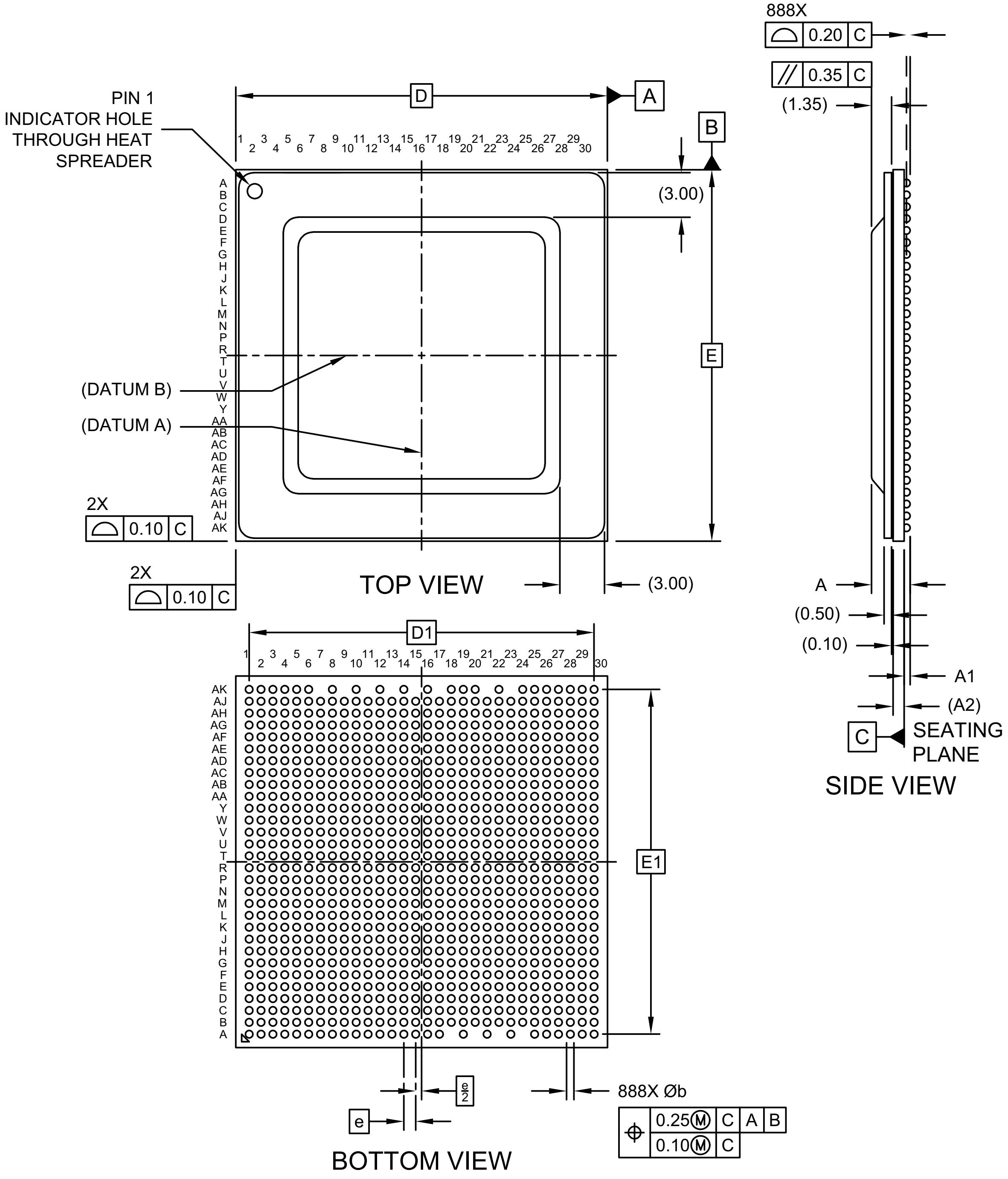
888-Ball Thick Fine Pitch Ball Grid Array (5CC) - 25x25x2.848 mm Body [HBFBGA] With Heat Spreader

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



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888-Ball Thick Fine Pitch Ball Grid Array (5CC) - 25x25x2.848 mm Body [HBFBGA] With Heat Spreader

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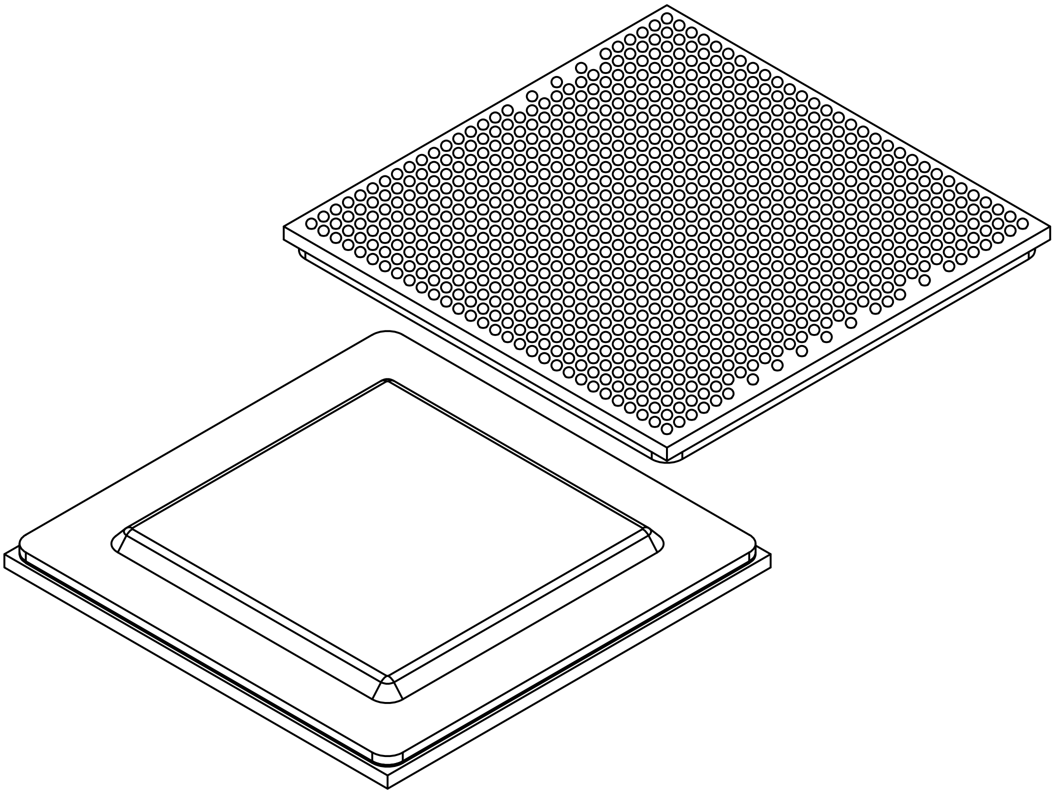

		Units	MILLIMETERS		
		Dimension Limits	MIN	NOM	MAX
Number of Terminals	N		888		
Pitch	e		0.80 BSC		
Overall Height	A		2.348	2.598	2.848
Standoff	A1		0.30	-	0.50
Substrate Thickness	A2		0.748 REF		
Overall Length	D		25.00 BSC		
Overall Ball Pitch	D1		23.20 BSC		
Overall Width	E		25.00 BSC		
Overall Ball Pitch	E1		23.20 BSC		
Terminal Width	b		0.40	-	0.60

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only, shown in parentheses.

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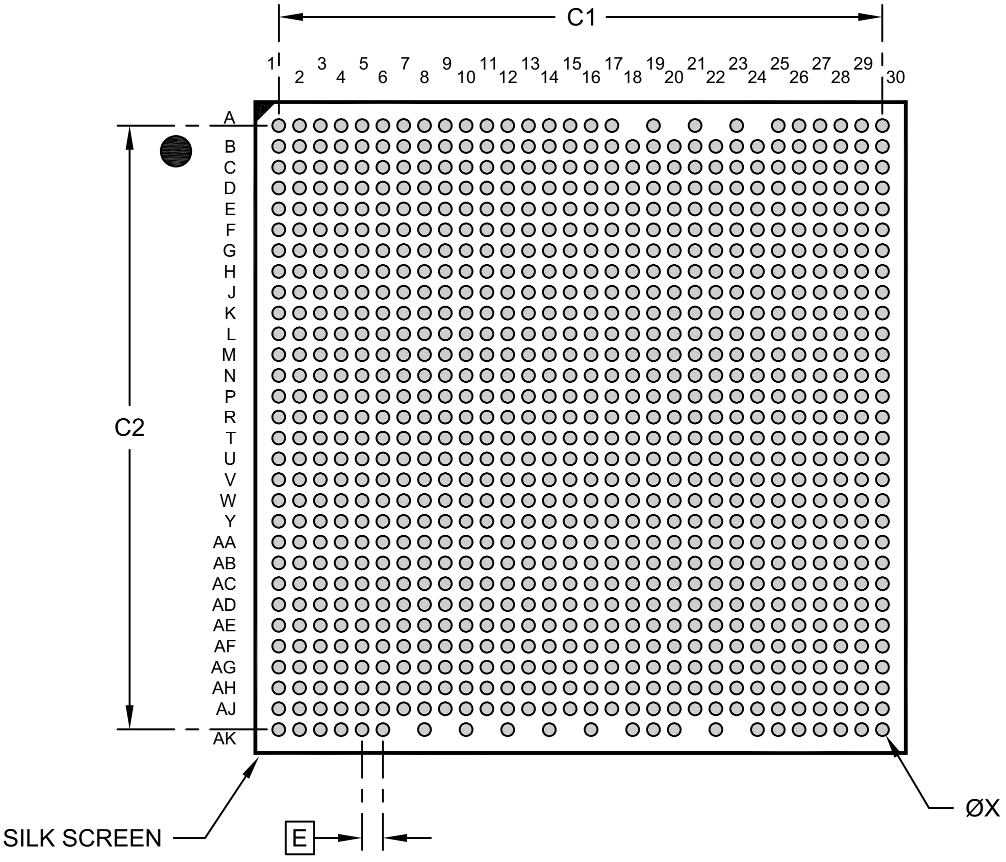

RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.80 BSC		
Contact Pad Spacing	C1		23.20	
Contact Pad Spacing	C2		23.20	
Contact Pad Diameter (X888)	X			0.50

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

2. Diameter of solder mask opening is 0.48 ±0.05 mm

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